Acquisition of an R&D business in wafer bonding from Nikon

SCREEN Holdings Co., Ltd. (SCREEN HD, President & CEO: Masato Goto) hereby announces the acquisition of an R&D business in wafer bonding from Nikon Corporation (Nikon; headquarters: Tokyo; Representative Director and Chairman: Toshikazu Umatate), effective on September 30.

In the semiconductor advanced packaging field, expectations are rising for more high-precision wafer bonding to support the increasing demand for footprint- and energy-saving devices. Positioning advanced packaging as a focus field, in addition to the sales of direct imaging systems and coater/dryer systems, we are working on the development and roll-out of low-temperature wafer bonding. The latest acquisition will allow us to combine Nikon's ultra-high-precision bonding technology with our proprietary technology as we seek to lead the world in bonding technology and establish a presence in this field.

Under the current medium-term management plan, Value Up Further 2026, covering the three fiscal years ending March 2027, SCREEN has been investing intensively for growth. In particular, we focus on advanced packaging as a new business field with a high growth potential, leading to the latest acquisition. The acquisition has already been reflected in the business plan for this fiscal year and therefore will not impart our earnings forecasts.

SCREEN will continue serving diverse client needs in the semiconductor packaging industry and contribute to its further development.

Overview of the acquisition

1. Acquired business	Nikon's R&D business in wafer bonding
2. Acquired from	NIKON CORPORATION Headquarters: 1-5-20 Nishioi, Shinagawa-ku, Tokyo, Japan Representative Director and Chairman: Toshikazu Umatate Capitalization: JPY 65,476 million (as of March 31, 2025) Established: July 25, 1917
3. Date of agreement	August 14, 2025
4. Date of acquisition	September 30, 2025

Inquiries:
Public Relations Unit, Corporate Communications Dept.
+81-75-414-7131 nr-info@screen.co.jp
SCREEN Holdings Co., Ltd.